L Number	Hits	Search Text	DB	Time stamp
62	52	(providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18
63	2	("5249100" | "6300678").PN.	USPAT	2002/07/12 15:58
64	6	5249100.URPN.	USPAT	2002/07/12 15:59
65	4	("3645785" | "3855693" | "4702941" | "4918811").PN.	USPAT	2002/07/12 15:59
66	1	6300678.URPN.	USPAT	2002/07/12 16:00
67	9	("4949455" | "5041901" | "5061552" | "5145104" | "5334804" | "5410807" | "5533665" | "5642261" | "5912510").PN.	USPAT	2002/07/12 16:00
68	9	("4949455" | "5041901" | "5061552" | "5145104" | "5334804" | "5410807" | "5533665" | "5642261" | "5912510").PN.	USPAT	2002/07/12 16:02
69	0	6413849.URPN.	USPAT	2002/07/12 16:02
70	8	("4634041" | "4970570" | "5442239" | "5448016" | "5640052" | "5718367" | "6054652" | "6077725").PN.	USPAT	2002/07/12 16:03
71	17	5640052.URPN.	USPAT	2002/07/12 16:04
72	2	6054652.URPN.	USPAT	2002/07/12 16:08
73	8	("4634041" | "4970570" | "5442239" | "5448016" | "5640052" | "5718367" | "6054652" | "6077725").PN.	USPAT	2002/07/12 16:09
74	0	6413849.URPN.	USPAT	2002/07/12 16:09
75	8	("4634041" | "4970570" | "5442239" | "5448016" | "5640052" | "5718367" | "6054652" | "6077725").PN.	USPAT	2002/07/12 16:09
76	4	("5421083" | "5432675" | "5543586" | "5834705").PN.	USPAT	2002/07/12 16:09
77	5986	((pin adj grid adj array) pga) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
78	170	(((pin adj grid adj array) pga) and (method process)) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
79	55	((((pin adj grid adj array) pga) and (method process)) and jig) and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:14
80	51	(((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:15
81	12	((((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))) and substrate and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:16
82	107	(providing near3 substrate) and ((attaching soldering) near3 pin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:18

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| 83 | 2 | (providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/07/12 16:31 |
| 84 | 18 | ((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polyimide plastic)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/07/12 16:33 |